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SURFBOARDS[®]

THE BREADBOARDING MEDIUM FOR **SURFACE MOUNT**™



33000 SERIES APPLICATION SPECIFIC ADAPTERS

IDS33306
REV A-10-2011

MODEL **33306**

ACCEPTS
(PARTIAL LISTING)

ON SEMI

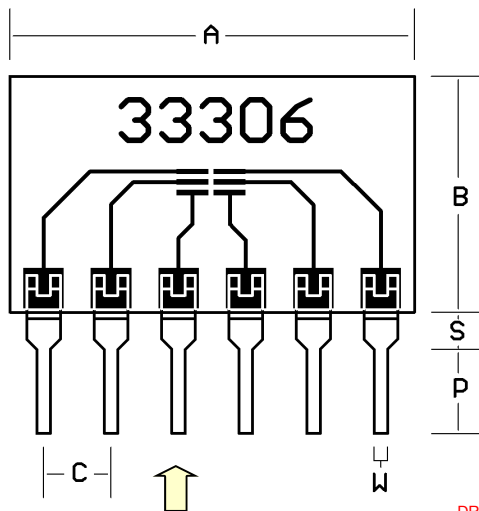
ULLGA6 1.2x1.0,0.4P
WDFN6 1.2x1.0,0.4P
WDFN6 1.25x1.0,0.4P

6 LEAD .4 mm PITCH DEVICES

DEVICE LEAD WIDTH 1.0 To Max 2.3 MM

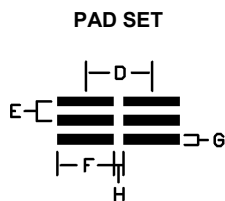
RENESAS **6L2MM (1208 PKG)**

ALWAYS CONSULT DEVICE DATA SHEET TO INSURE PROPER FIT

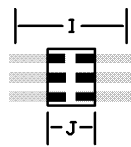


SINGLE-IN-LINE (SIP) PINS
ON .100 in. CENTERS

DRAWINGS
NOT TO
SCALE



EXAMPLE DEVICE (J)
AND MAX WIDTH (I)



MOUNTING PADS ARE OVERSIZED IN LENGTH TO
ACCEPT A WIDER RANGE OF DEVICE WIDTHS AND
TOLERANCES AND TO PERMIT HAND SOLDERING.

SEE WEBSITE FOR SOLDERING SUGGESTIONS

Pins on .1 in. Centers designed for use with Solderless breadboards, Conventional Breadboards, and Sockets with standard .1 in. centers.

Use For Prototyping, Device Test or Evaluation and SMD to Through Hole Conversion.

Oversize Pads Permit hand soldering and accept a wide range of device widths and tolerances.

FIG.	MM	IN.	NOTE:
A	15.24	.600	BOARD WIDTH +/- .5mm .020in.
B	8.89	.350	BOARD HEIGHT +/- .5mm .020in.
C	2.54	.100	SIP PIN SPACE +/- .20mm .008in.
D	1.4	.055	PAD CENTERLINE
E	.4	.016	DEVICE LEAD PITCH
F	1.2	.047	PAD LENGTH
G	.22	.009	PAD WIDTH
H	.2	.008	GAP
I	2.3	.090	MAX LEAD WIDTH
J	1.0	.039	TYPICAL LEAD WIDTH
P	3.3	.130	LENGTH FROM SHOULDER +/- .5mm .020in.
S	1.57	.062	PIN SHOULDER HEIGHT
W	.5	.020	PIN WIDTH

TOLERANCES: If not noted are +/- 20%. Nominal values are given. Controlling unit is Millimeters. Slight Variations due to manufacturing process can occur.

BOARD SPECIFICATIONS

BOARD MATERIAL: .8mm, +/- .13mm .031in +/- .005 in. Thick G-10 FR-4 Glass Epoxy or equivalent.

CIRCUITS: 1 oz. Copper with RoHS compliant Lead Free solder coating. Patten Position on board +/- .5mm .020in.



RoHS
Compliant
EC 2002/95

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